

Test Items 測試項目	Test Conditions 測試條件	Sampling Plan 抽樣計劃	Frequency 頻率
<b>High Temperature Storage Test</b> 高溫貯存測試	$T_a = T_{stg \text{ Max.}} \pm 5^\circ\text{C}$ 168+16/-10 hrs	Sample size : 40 pcs Ac/Re: 0/1	Once / Month
<b>Low Temperature Storage Test</b> 低溫貯存測試	$T_a = T_{stg \text{ Min.}} \pm 5^\circ\text{C}$ 168+16/-10 hrs	Sample size : 40 pcs Ac/Re: 0/1	Once / Month
<b>High Temperature Reverse Bias Test (HTRB)</b> 高溫直流反向偏壓測試	$V_{CB} = V_{CBO \text{ Max.}}$ , $R_L = 1\text{M}\Omega$ 168+16/-10 hrs $T_a = T_j \pm 5^\circ\text{C}$	Sample size : 40 pcs Ac/Re: 0/1	Once / Month
<b>Continuous Operation Test</b> 工作壽命測試	$V_{CE} = 0.7V_{CEO \text{ Max.}}$ , $I_C = P_{tot}/V_{CE}$ $R_L = 100\Omega$ , $T_a = 25 \pm 5^\circ\text{C}$ 168+16/-10 hrs	Sample size : 40 pcs Ac/Re: 0/1	Once / Month
<b>Constant Temperature/Humidity Storage Test</b> 恆溫恆濕儲存測試	$V_{CB} = V_{CBO \text{ Max.}}$ , $T_a = 85 \pm 5^\circ\text{C}$ RH=85±5%, 168+16/-10 hrs	Sample size : 40 pcs Ac/Re: 0/1	Once / Month
<b>Temperature Cycling Test</b> 溫度循環測試	$T_{stg \text{ Min.}}$ , 30+2/-0 min ; 25±5°C, 10+2/-0 min ; $T_{stg \text{ Max.}}$ , 30+2/-0 min ; 25±5°C, 10+2/-0 min; (10 Cycles)	Sample size : 40 pcs Ac/Re: 0/1	Once / Month
<b>High Pressure / High Humidity / High Temperature Test (PCT)</b> 高壓 / 高濕 / 高溫測試	Vapor Pressure=1.05kg/cm <sup>2</sup> RH=100%, $T_a = 121^\circ\text{C}$ 24+2/-0 hrs	Sample size : 40 pcs Ac/Re: 0/1	Once / Month
<b>Solder Heat Resistance Test</b> 耐焊接測試	Solder temperature: 260±5°C immersion time: 10+2/-0 sec	Sample size : 40 pcs Ac/Re: 0/1	Once / Month
<b>Solderability Test</b> 可焊性測試	245±5°C for 5±1sec(SOT) 245±3°C for 5±1sec(TO-92) Sn100%	Sample size : 10 pcs Ac/Re: 0/1	Once / Month